AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph on page 1, lines 12-24 of the specification as filed with the following:

Transfer molding of thermo setting plastics is a well known and commonly used technique for packaging an integrated circuit (IC). The transfer molding process molds a liquefied plastic material around portions of an IC. A transfer mold is placed over the IC and the transfer mold is filled with liquefied ~~thermo setting~~ thermosetting plastic material. After the liquefied ~~thermo setting~~ thermosetting plastic material has been compacted and solidified, the transfer mold is removed from the IC. The solidified plastic material provides mechanical and environmental protection for the encapsulated IC. An exemplary transfer molding process will be more fully described with reference to FIGURES 1 though 5.

Please replace the paragraph bridging page 7, line 20 to page 8, line 10 of the specification as filed with the following:

The foregoing has outlined rather broadly the features and technical advantages of the present invention so that those skilled in the art may better understand the detailed description of the invention that follows. Additional features and advantages of the invention will be described hereinafter that form the subject of the claims of the invention. Those skilled in the art will appreciate that they may

readily use the ~~conception~~ concepts and the specific embodiment disclosed as a basis for modifying or designing other structures for carrying out the same purposes of the present invention. Those skilled in the art will also realize that such equivalent constructions do not depart from the spirit and scope of the invention in its broadest form.

Please replace the paragraph bridging page 10, line 22 to page 11, line 13 of the specification as filed with the following:

FIGURE 4 illustrates a sectional side view of an exemplary prior art transfer mold lowered into place over an integrated circuit die on an integrated circuit substrate in which the cavity or cavities of the transfer mold are filled with plastic molding compound;

Please replace the paragraphs on page 12, lines 11-23 of the specification as filed with the following:

FIGURE 1 illustrates a sectional side view of an exemplary prior art transfer mold 100. Exemplary transfer mold 100 comprises portions that form a channel 120 and a channel 122 that extend through the body of transfer mold 100. Channel 120 and channel 122 extend from a first mold cavity region 130 formed by the lower

surface 140 of transfer mold 100 to the upper exterior surface 150 of transfer mold 100.

Exemplary transfer mold 100 also comprises portions that form channels 160, 162, 164 and 166 that extend through the body of transfer mold 100. Channels 160, 162, 164 and 166 extend from a second mold cavity region 170 formed by the lower surface 140 of transfer mold 100 to the upper exterior surface 150 of transfer mold 100.

Please replace the paragraphs bridging page 13, line 11 to page 15, line 12 of the specification as filed with the following:

As shown in FIGURE 1, film 200 completely covers the lower surface 140 of transfer mold 100. Film 200 is placed across the bottom of transfer mold 100 so that film 200 seals mold cavity region 130 and mold cavity region 170. At this point mold cavity region 130 has access to the atmosphere through channel 120 and channel 122 and mold cavity region 170 has access to the atmosphere through channels 160, 162, 164 and 166.

A vacuum pump (not shown) is connected to the openings of channels 120, 122, 160, 162, 164 and 166 in the upper exterior surface 150 of transfer mold 100. The vacuum pump is activated to pump out the air from within mold cavity region 130 and from within mold cavity region 170. As the air is removed through the channels 120, 122, 160, 162, 164 and 166, the atmospheric pressure on the external

surface of film 200 forces film 200 against the lower surface 140 of transfer mold 100. As shown in FIGURE 2, film 200 stretches and becomes fitted into place against the mold contours of the lower surface 140 of transfer mold 100.

After film 200 has been fitted into place against the mold contours of the lower surface 140 of transfer mold 100, transfer mold 100 is lowered into position on top of integrated circuit die 180 and integrated circuit substrate 190. FIGURE 3 illustrates how transfer mold 100 fits into place over integrated circuit die 180 and integrated circuit substrate 190. Film 200 rests on the surface of integrated circuit die 180 and protects it from touching the body of transfer mold 100. In the example shown in FIGURE 3, the left end portion of integrated circuit die 180 extends into mold cavity region 170.

FIGURE 4 illustrates a sectional side view of transfer mold 100 lowered into place over integrated circuit die 180 and integrated circuit substrate 190 in which mold cavity region 130 and mold cavity region 170 have been filled with molding compound. The molding compound usually comprises thermo setting plastic material 300. Liquefied plastic material 300 is injected under pressure into mold cavity region 130 and into mold cavity region 170 through one or more separate channels (not shown) through transfer mold 100.

As shown in FIGURE 5, after the liquefied plastic material 300 within mold cavity region 130 and within mold cavity region 170 has been compacted and solidified, the transfer mold 100 is separated from the combination that comprises integrated circuit die 180, integrated circuit substrate 190, and solidified plastic

material 300. The solidified plastic material 300 provides mechanical and environmental protection for the integrated circuit die 180. As also shown in FIGURE 5, an exposed portion 320 of integrated circuit die 180 remains open to the atmosphere.

Please replace the paragraph on page 20, lines 13-21 of the specification as filed with the following:

The first step of the method is to provide a film 600 of compliant material (step 910). Then film 600 is pre-formed to conform the shape of film 600 to the surface of the mold cavity of transfer mold 100 (step 920). Then pre-formed film 600 is placed within the mold cavity of transfer mold 100 (step 930). As previously described, pre-formed film 600 may be held in place within the mold cavity of transfer mold 100 by applying a vacuum to one or more of channels 120, 122, 160, 162, 164 and 166 of transfer mold 100 (with film 600 covering the opening(s) into cavity regions 130, 170 of the corresponding channel(s)).